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In re application of

Confirmation No. 9620

Masanobu NOGOME et al.

Docket No. 2003 1075A

Serial No. 10/630,900

Group Art Unit 2818

Filed July 31, 2003

Examiner Mai Huong Tran

SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREOF

RESPONSE TO NOTICE OF NON-COMPLIANT AMENDMENT

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450 THE COMMISSIONER IS AUTHORIZED TO CHARGE ANY DEFICIENCY IN THE FEES FOR THIS PAPER TO DEPOSIT ACCOUNT NO. 23-0975

Sir:

Please find attached an Amendment in response to the Notice of Non-Compliant Amendment dated April 19, 2005. The attached Amendment is identical to the Amendment submitted on April 19, 2005, with the only exception being that the amended title includes markings.

Respectfully submitted,

Masanobu NOGOME et al.

By:

W. Døuglas Hahm

Registration No. 44,142

Attorney for Applicants

WDH/ck Washington, D.C. 20006-1021 Telephone (202) 721-8200 Facsimile (202) 721-8250 April 28, 2005



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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AMENDMENT

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450 THE COMMISSIONER IS AUTHORIZED TO CHARGE ANY DEFICIENCY IN THE FEES FOR THIS PAPER TO DEPOSIT ACCOUNT NO. 23-0975

Sir:

Responsive to the Office Action dated March 22, 2005, please amend the above-identified application as follows.



AMENDMENT TO THE TITLE

Please replace the original title with following rewritten title.

Semiconductor Device and Manufacturing Method Thereof Including a Photosensitive

Resin Covering at Least a Portion of a Substrate Having a via Hole